DIMENSO SERIES

LASER PROCESSING AND MECHANICAL SCRIBING
FOR THIN FILM APPLICATIONS ON LARGE AREA SUBSTRATES
FEATURES
◆ High speed processing with multiple beams for increased throughput
◆ Fixed optic or scanner concept available
◆ Precise pattern accuracy based on highly accurate machine vision systems
◆ Integrated sensors to automatically compensate substrate tolerances
◆ Minimized substrate contact reduces defects and contamination

OPTIONS
◆ Through the glass or film side processing
◆ SQL data base for process and event tracking
◆ MES interface
◆ Integrated process metrology
◆ Simultaneous processing of two panels
◆ External substrate transport system

APPLICATIONS
Thin film ablation, laser and mechanical scribing (P1/P2/P3/P4), laser edge deletion, TCO patterning, glass cutting

ACCURACY
< +/- 25 µm (1 sigma)
< +/- 10 µm optionally
< +/- 2 µm repeatability

SUBSTRATES
Dimensions up to 2500 mm x 1500 mm
Various substrate thicknesses

AVAILABLE LASER SOURCES
Wavelength: 1064, 1030, 532, 515, 355, 343 nm
Pulse duration: µs, ns, ps, fs

DIMENSIONS
3800 x 3150 x 2800 mm
(depending on substrate size)